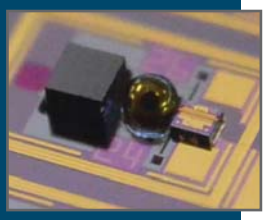
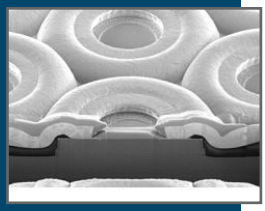
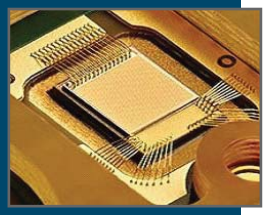
Advanced Packaging Update:
Market and Technology Trends

Vol. 1-0518







This issue of the Advanced Packaging Update features special coverage of outsourced semiconductor assembly and test (OSAT) financials. A discussion of fan-out wafer level package (FO-WLP) trends, including TSMC's latest portfolio and an update on large-area panel activities are provided. The growing applications for 3D sensing are discussed along with details on VCSEL technology. Integrated photonics packaging trends are presented.

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